

MC10H181

4-Bit Arithmetic Logic Unit/ Function Generator

The MC10H181 is a high-speed arithmetic logic unit capable of performing 16 logic operations and 16 arithmetic operations on two four-bit words. Full internal carry is incorporated for ripple through operation.

Arithmetic logic operations are selected by applying the appropriate binary word to the select inputs (S0 through S3) as indicated in the tables of arithmetic/logic functions. Group carry propagate (PG) and carry generate (GG) are provided to allow fast operations on very long words using a second order look-ahead. The internal carry is enabled by applying a low level voltage to the mode control input (M).

When used with the MC10H179, full-carry look-ahead, as a second order look-ahead block, the MC10H181 provides high-speed arithmetic operations on very long words.

This 10H part is a functional/pinout duplication of the standard MECL 10K family part with 100% improvement in propagation delay and no increase in power supply current.

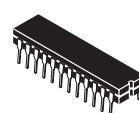
- Improved Noise Margin, 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K – Compatible



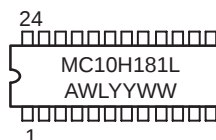
ON Semiconductor

<http://onsemi.com>

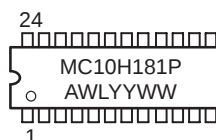
MARKING DIAGRAMS



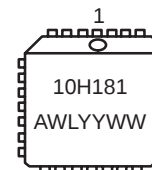
**CDIP-24
L SUFFIX
CASE 758**



**PDIP-24
P SUFFIX
CASE 724**



**PLCC-28
FN SUFFIX
CASE 776**



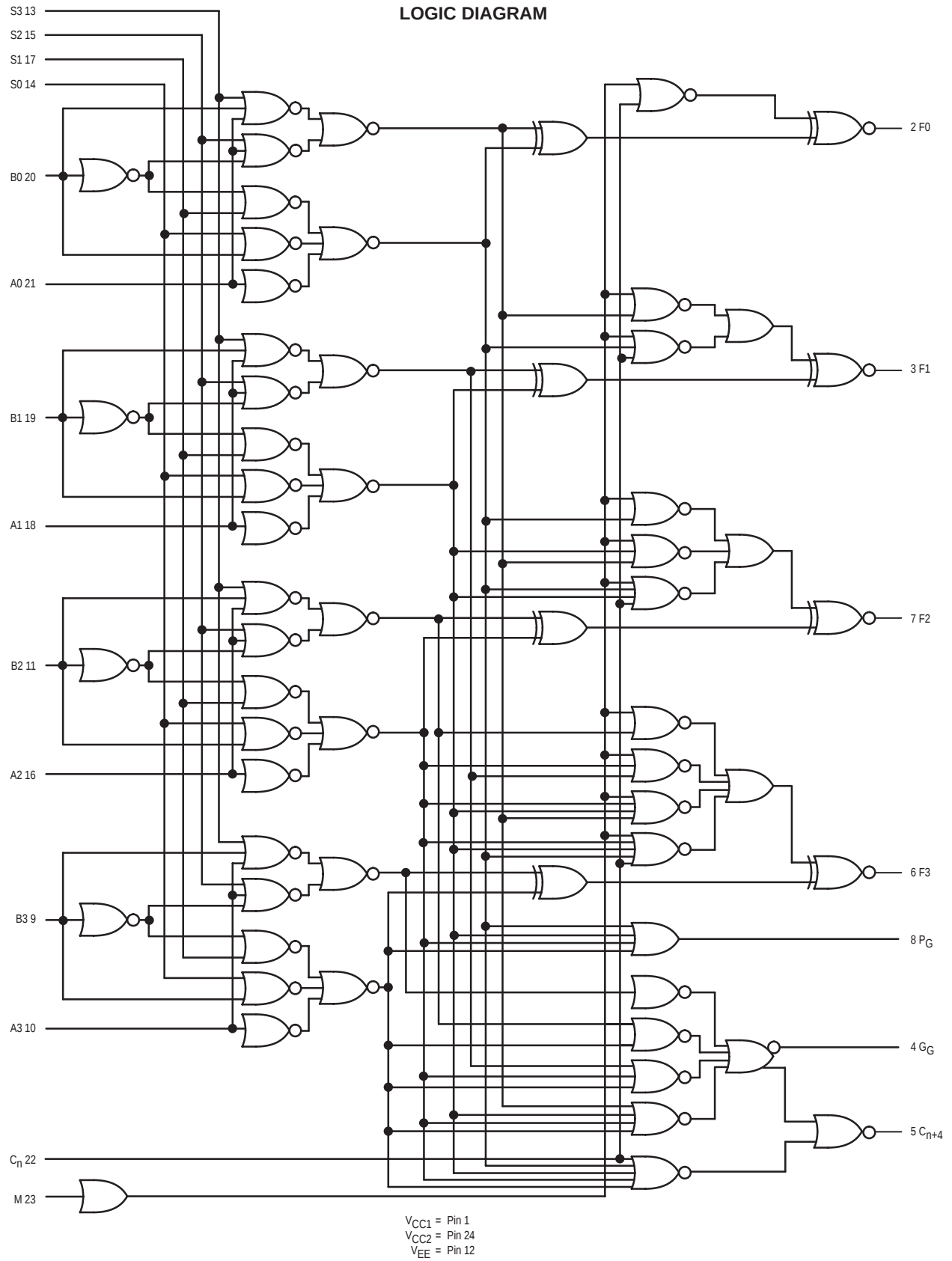
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

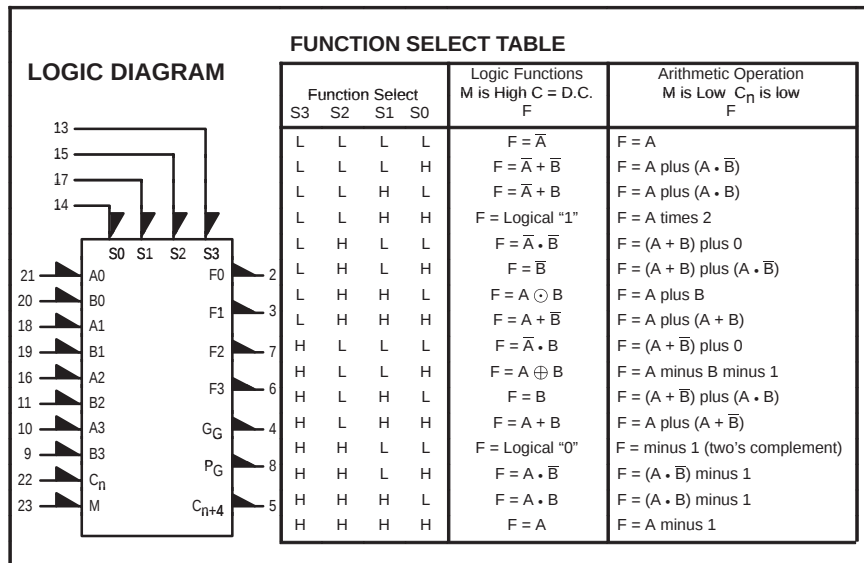
Device	Package	Shipping
MC10H181L	CDIP-24	15 Units/Rail
MC10H181P	PDIP-24	15 Units/Rail
MC10H181FN	PLCC-28	37 Units/Rail

MC10H181

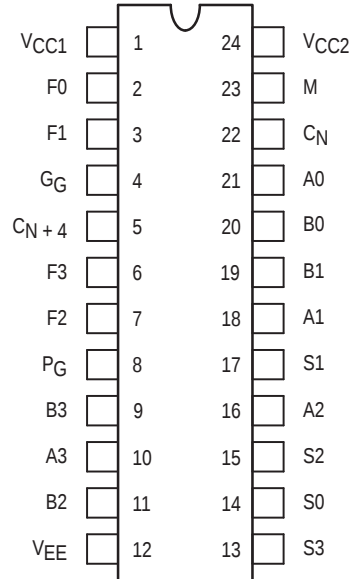
LOGIC DIAGRAM



MC10H181



DIP PIN ASSIGNMENT



Pin assignment is for Dual-In-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18
of the ON Semiconductor MECL Data Book (DL122/D).

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply ($V_{CC} = 0$)	-8.0 to 0	Vdc
V_I	Input Voltage ($V_{CC} = 0$)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	-55 to +150 -55 to +165	°C °C

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ELECTRICAL CHARACTERISTICS ($V_{EE} = -5.2 \text{ V} \pm 5.0\%$) (See Note 1.)

Characteristic	Symbol	0°		+25°		+75°		Unit
		Min	Max	Min	Max	Min	Max	
Power Supply Current	I_E	—	159	—	145	—	159	mA
Input Current High	I_{inH}	—	720	—	450	—	450	μA
Pin 22		—	405	—	255	—	255	
Pins 14,23		—	515	—	320	—	320	
Pins 13,15,17		—	475	—	300	—	300	
Pins 10,16,18,21		—	465	—	275	—	275	
Pins 9,11,19,20								
Input Current Low	I_{inL}	0.5	—	0.5	—	0.3	—	μA
Pins 9–11, 13–22								
High Output Voltage	V_{OH}	–1.02	–0.84	–0.98	–0.81	–0.92	–0.735	Vdc
Low Output Voltage	V_{OL}	–1.95	–1.63	–1.95	–1.63	–1.95	–1.60	Vdc
High Input Voltage	V_{IH}	–1.17	–0.84	–1.13	–0.81	–1.07	–0.735	Vdc
Low Input Voltage	V_{IL}	–1.95	–1.48	–1.95	–1.48	–1.95	–1.45	Vdc

1. Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts.

AC PARAMETERS

Characteristic	Symbol	Input	Output	Conditions †	AC Switching Characteristics						
					0°C		+25°C		+75°C		Unit
					Min	Max	Min	Max	Min	Max	
Propagation Delay	t+ +, t- -	Cn	Cn+4	A0,A1,A2,A3	0.7	2.0	0.7	2.0	0.7	2.2	ns
Rise Time, Fall Time	t+, t-	Cn	Cn+4	A0,A1,A2,A3	0.6	2.0	0.6	2.0	0.7	2.2	ns
Propagation Delay	t+ +, t+ -, t- +, t- -	Cn	F1	A0	1.0	3.0	1.0	3.0	1.2	3.3	ns
Rise Time, Fall Time	t+, t-	Cn	F1		0.7	2.2	0.7	2.2	0.7	2.4	
Propagation Delay	t+ +, t+ -, t- +, t- -	A1	F1		1.5	3.7	1.5	3.7	1.6	4.0	ns
Rise Time, Fall Time	t+, t-	A1	F1		0.7	2.0	0.7	2.0	0.7	2.2	
Propagation Delay	t+ +, t- -	A1	PG	S0,S3	1.5	3.7	1.5	3.7	1.6	4.0	ns
Rise Time, Fall Time	t+, t-	A1	PG	S0,S3	0.9	2.4	0.9	2.4	0.9	2.6	ns
Propagation Delay	t+ +, t- -	A1	GG	A0,A2,A3,Cn	1.5	3.7	1.5	3.7	1.6	3.9	ns
Rise Time, Fall Time	t+, t-	A1	GG	A0,A2,A3,Cn	0.7	2.2	0.7	2.2	0.7	2.4	ns
Propagation Delay	t+ -, t- +	A1	Cn+4	A0,A2,A3,Cn	1.5	3.6	1.5	3.6	1.6	3.9	ns
Rise Time, Fall Time	t+, t-	A1	Cn+4	A0,A2,A3,Cn	0.5	2.0	0.5	2.0	0.5	2.2	ns
Propagation Delay	t+ +, t- +	B1	F1	S3,Cn	2.0	4.5	2.0	4.5	2.1	4.8	ns
Rise Time, Fall Time	t+, t-	B1	F	S3,Cn	0.7	2.3	0.7	2.3	0.7	2.5	ns
Propagation Delay	t+ +, t- -	B1	PG	S0,A1	1.5	3.8	1.5	3.8	1.6	4.0	ns
Rise Time, Fall Time	t+, t-	B1	PG	S0,A1	0.7	2.2	0.7	2.2	0.7	2.4	ns
Propagation Delay	t+ +, t- -	B1	GG	S3,Cn	1.5	3.7	1.5	3.7	1.6	4.0	ns
Rise Time, Fall Time	t+, t-	B1	GG	S3,Cn	0.7	2.2	0.7	2.2	0.7	2.4	ns
Propagation Delay	t+ -, t- +	B1	Cn+4	S3,Cn	2.0	4.0	2.0	4.0	2.1	4.3	ns
Rise Time, Fall Time	t+, t-	B1	Cn+4	S3,Cn	0.5	2.0	0.5	2.2	0.5	2.2	ns
Propagation Delay	t+ +, t+ -	M	F1	-	1.5	4.2	1.5	4.2	1.6	4.5	ns
Rise Time, Fall Time	t+, t-	M	F1	-	0.8	2.3	0.8	2.3	0.8	2.5	ns
Propagation Delay	t+ -, t- +	S1	F1	A1,B1	1.5	4.5	1.5	4.5	1.6	4.8	ns
Rise Time, Fall Time	t+, t-	S1	F1	A1,B1	0.7	2.0	0.7	2.0	0.7	2.2	ns
Propagation Delay	t- +, t+ -	S1	PG	A3,B3	1.5	4.0	1.5	4.0	1.6	4.3	ns
Rise Time, Fall Time	t+, t-	S1	PG	A3,B3	0.7	2.0	0.7	2.2	0.7	2.4	ns
Propagation Delay	t+ -, t- +	S1	Cn+4	A3,B3	1.5	4.1	1.5	4.1	1.6	4.4	ns
Rise Time, Fall Time	t+, t-	S1	Cn+4	A3,B3	0.7	2.2	0.7	2.2	0.7	2.4	ns
Propagation Delay	t+ -, t- +	S1	GG	A3,B3	1.3	4.5	1.3	4.5	1.4	4.8	ns
Rise Time, Fall Time	t+, t-	S1	GG	A3,B3	0.5	3.2	0.5	3.2	0.5	3.4	ns

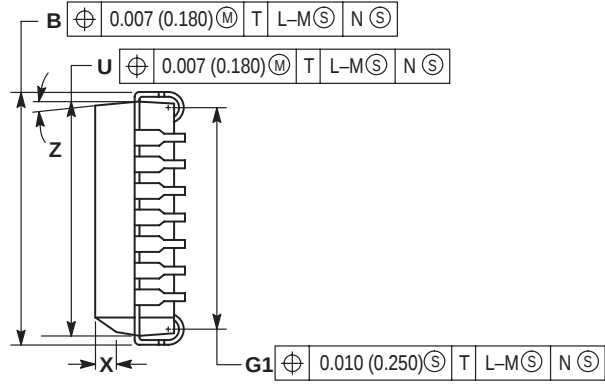
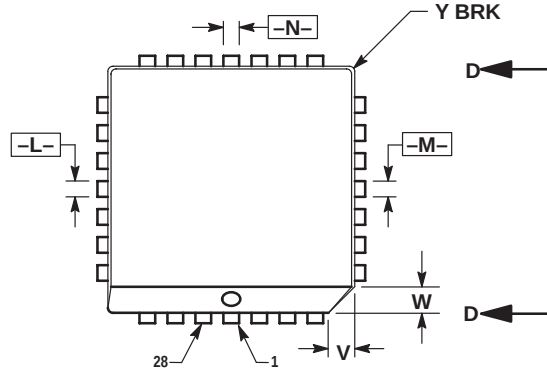
† Logic high level (+1.11 Vdc) applied to pins listed. All other input pins are left floating or tied to +0.31 Vdc.

$V_{CC1} = V_{CC2} = +2.0 \text{ Vdc}$, $V_{EE} = -3.2 \text{ Vdc}$

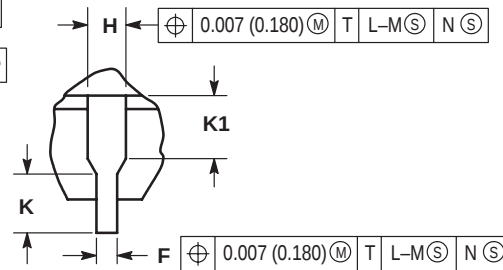
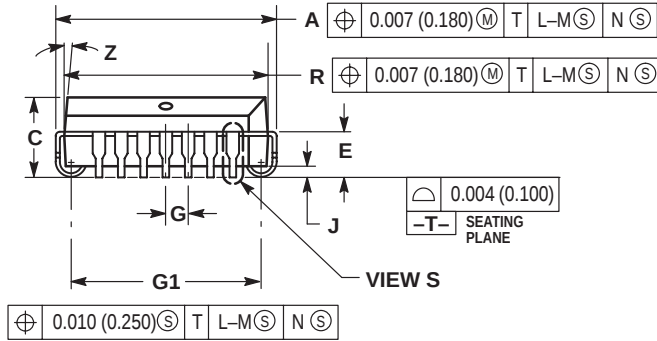
MC10H181

PACKAGE DIMENSIONS

PLCC-28
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 776-02
ISSUE D



VIEW D-D



VIEW S

NOTES:

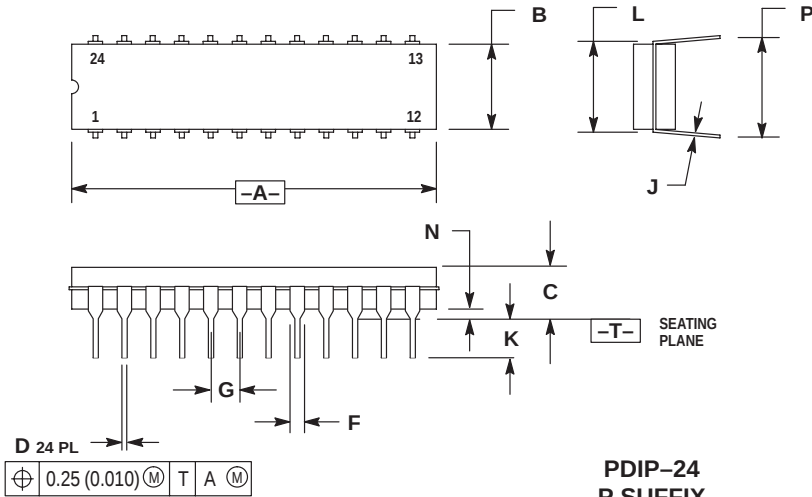
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

MC10H181

PACKAGE DIMENSIONS

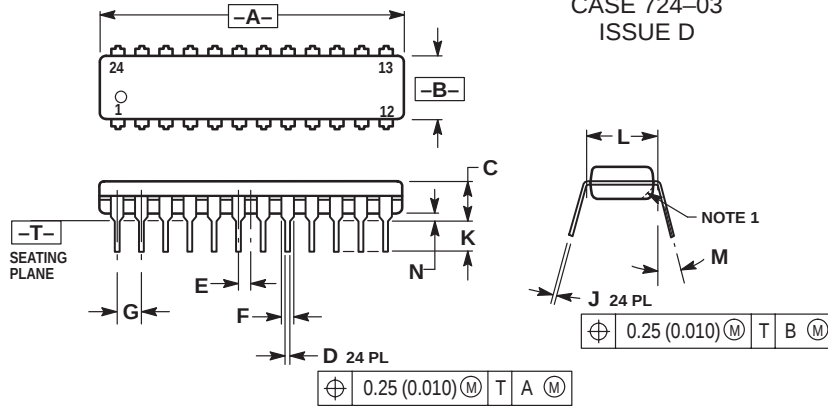
CDIP-24 L SUFFIX CERAMIC DIP PACKAGE CASE 758-02 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.285	31.50	32.64
B	0.285	0.305	7.24	7.75
C	0.160	0.200	4.07	5.08
D	0.015	0.021	0.38	0.53
F	0.045	0.062	1.14	1.57
G	0.100 BSC		2.54 BSC	
J	0.008	0.013	0.20	0.33
K	0.100	0.165	2.54	4.19
L	0.300	0.310	7.62	7.87
N	0.020	0.050	0.51	1.27
P	0.360	0.400	9.14	10.16

PDIP-24 P SUFFIX PLASTIC DIP PACKAGE CASE 724-03 ISSUE D



- NOTES:
1. CHAMFERED CONTOUR OPTIONAL.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 4. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.230	1.265	31.25	32.13
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
E	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100 BSC		2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

Notes

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Toll Free from Hong Kong 800-4422-3781
Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549

Phone: 81-3-5740-2745
Email: r14525@onsemi.com

Fax Response Line: 303-675-2167
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